



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC0804NLS	Issued	23. June 2021
MA#	MA005431518		
Package	PG-TDSON-8-45	Weight*	118.09 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.510	0.43	0.43	4315	4315
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	iron	7439-89-6	0.038	0.03		320	
	non noble metal	copper	7440-50-8	37.762	31.97	32.01	319775	320191
wire	noble metal	gold	7440-57-5	0.047	0.04	0.04	401	401
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		740	
	plastics	epoxy resin	-	6.900	5.84		58433	
	inorganic material	silicondioxide	60676-86-0	36.685	31.07	36.98	310659	369832
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12293	12293
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1402	1402
solder	non noble metal	tin	7440-31-5	0.016	0.01		131	
	noble metal	silver	7440-22-4	0.019	0.02		164	
	non noble metal	lead	7439-92-1	0.740	0.63	0.66	6268	6563
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	iron	7439-89-6	0.022	0.02		189	
	non noble metal	copper	7440-50-8	22.292	18.88	18.91	188771	189017
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			29	
	non noble metal	iron	7439-89-6	0.011	0.01		96	
	non noble metal	copper	7440-50-8	11.320	9.59	9.60	95861	95986
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com